Docket No.: 4249-0112P Art Unit: 1762 Page 2 of 17

AMENDMENTS TO THE CLAIMS

 (Previously Presented) A method of producing a piezoelectric ceramic thick film on a substrate, said method comprising;

• mixing liquid phase precursors of ${\rm Li_2O}$ and ${\rm Bi_2O_3}$ metal oxides to form a Li-Bi solution:

 forming a suspension of a piezoelectric ceramic material in powder form and a fluid medium by ultrasonic vibration;

forming a liquid mixture by mixing the suspension of powdered material with the Li-Bi solution, the ${\rm Li_2O}$ and ${\rm Bi_2O_3}$ having melting points lower than a temperature required for densifying the piezoelectric ceramic thick film by sintering, said liquid mixture obtained by mixing the suspension of powdered material and the Li-Bi solution having a greater degree of homogeneity than that of a mixture obtained by mechanically mixing the powdered material;

- · drying the liquid mixture to form a dried precipitate;
- milling the dried precipitate to form a powdered precipitate;
- adding an organic carrier to the powdered precipitate;
- further milling the powdered precipitate to form a paste;
- depositing a layer of the paste, as a wet film, onto the substrate; and

annealing the substrate with the film at a temperature and for a time sufficient to cause transformation of the paste into the thick film.

Application No. 10/680,229 Reply date September 3, 2009

Reply to Office Action of April 3, 2009

Docket No.: 4249-0112P Art Unit: 1762

Page 3 of 17

2. (Original) A method according to claim 1, wherein the piezoelectric ceramic

material is an inorganic ceramic material which exhibits the piezoelectric effect.

3. (Original) A method according to claim 2, wherein the piezoelectric ceramic

material is lead zirconate titanate (PZT).

4. (Previously Presented) A method according to claim 1, wherein the Li₂O and Bi₂O₃

metal oxides are adapted to form a glass phase upon annealing at a temperature between 800°

and 1000°C.

5-11. (Cancelled)

12. (Previously Presented) A method according to claim 1, wherein the powdered

piezoelectric material is fine-grained having an average grain size of below about 1.0 µm.

13. (Previously Presented) A method according to claim 12, wherein the average

grain size is about 0.5 µm.

Application No. 10/680,229 Reply date September 3, 2009

Reply to Office Action of April 3, 2009

Docket No.: 4249-0112P Art Unit: 1762

Page 4 of 17

14. (Previously Presented) A method according to claim 1, wherein the total amount

of the Li₂O and Bi₂O₃ metal oxides in the thick film are between about 1% and 5%, by

weight.

15. (Cancelled)

16. (Previously Presented) A method according to claim 1, wherein the liquid mixture

is dried at a temperature between 75° and 150°C to form the dried precipitate.

17. (Original) A method according to claim 16, wherein the liquid mixture is dried at

a temperature between about 75°C and 105°C for up to 10 hours.

18. (Cancelled)

19. (Previously Presented) A method according to claim 1, wherein the powdered

precipitate is formed by milling the dried precipitate with a ball mill.

20. (Cancelled)

JMS/CTT/ktp

Application No. 10/680,229 Reply date September 3, 2009

Reply to Office Action of April 3, 2009

Docket No.: 4249-0112P Art Unit: 1762

Page 5 of 17

21. (Previously Presented) A method according to claim 1, wherein the organic

carrier is selected from one or more of ethyl cellulose, terpineol, and an organic binder

containing texanol.

22. (Previously Presented) A method according to claim 21, wherein the organic

carrier is the organic binder containing texanol.

23. (Cancelled)

24. (Previously Presented) A method according to claim 1, wherein the paste is

deposited onto a surface of the substrate, by a printing process, as the wet film.

25. (Original) A method according to claim 24, wherein the printing process is a

screen printing process.

26. (Previously Presented) A method according to claim 1, wherein, prior to

annealing, the layered substrate including the deposited wet film is dried.

27. (Previously Presented) A method according to claim 1, wherein, prior to

annealing, an isostatic pressure is applied to the film.

JMS/CTT/ktp

28. (Previously Presented) A method according to claim 26, wherein the drying

temperature of the layered substrate including the deposited wet film is between about 20°C

and about 175°C.

29. (Previously Presented) A method according to claim 1 wherein the layered

substrate is annealed at a temperature of between about 820°C and about 950°C.

30. (Original) A method according to claim 29, wherein the annealing is conducted

for between about 10 minutes and about 4 hours.

31. (Previously Presented) A method according to claim 1, wherein the substrate is

formed of silicon.

32. (Previously Presented) A method according to claim 1, wherein the surface of the

substrate has a coating of platinum and the paste is deposited on this platinum coating.

33. (Previously Presented) A method according to claim 1, wherein a metal electrode

is formed on the piezoelectric ceramic thick film.

34. (Previously Presented) A method according to claim 33, wherein the metal electrode is formed of silver and the electrode is deposited on the film by a screen printing process.

35-38. (Cancelled)

39. (New) A method according to claim 1, wherein the powdered precipitate is formed by milling the dried precipitate with a ball mill,

wherein the layered substrate is annealed at a temperature of between about 820°C and about 950°C for about 4 hours,

wherein a metal electrode is formed on the piezoelectric ceramic thick film.